



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



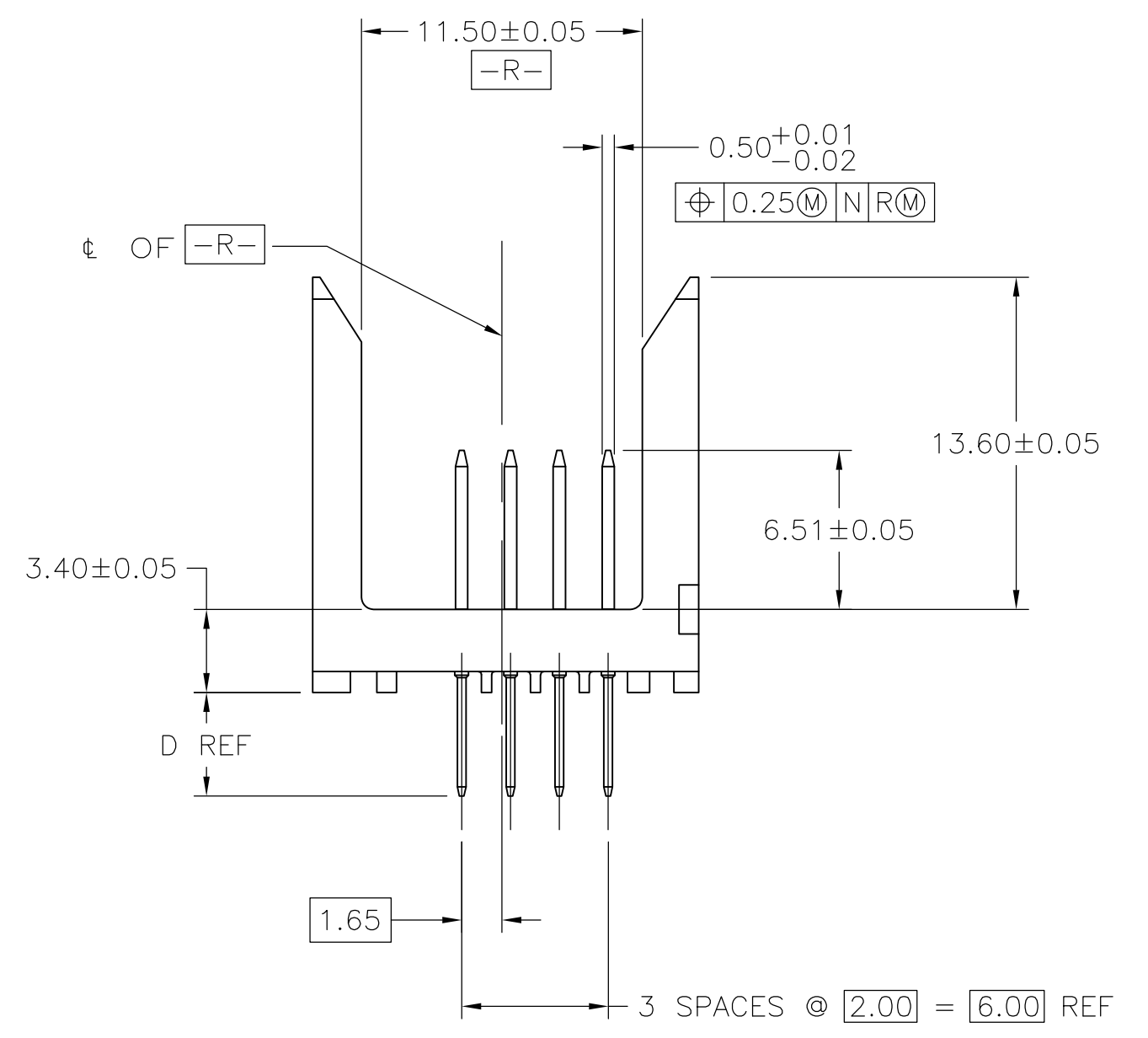
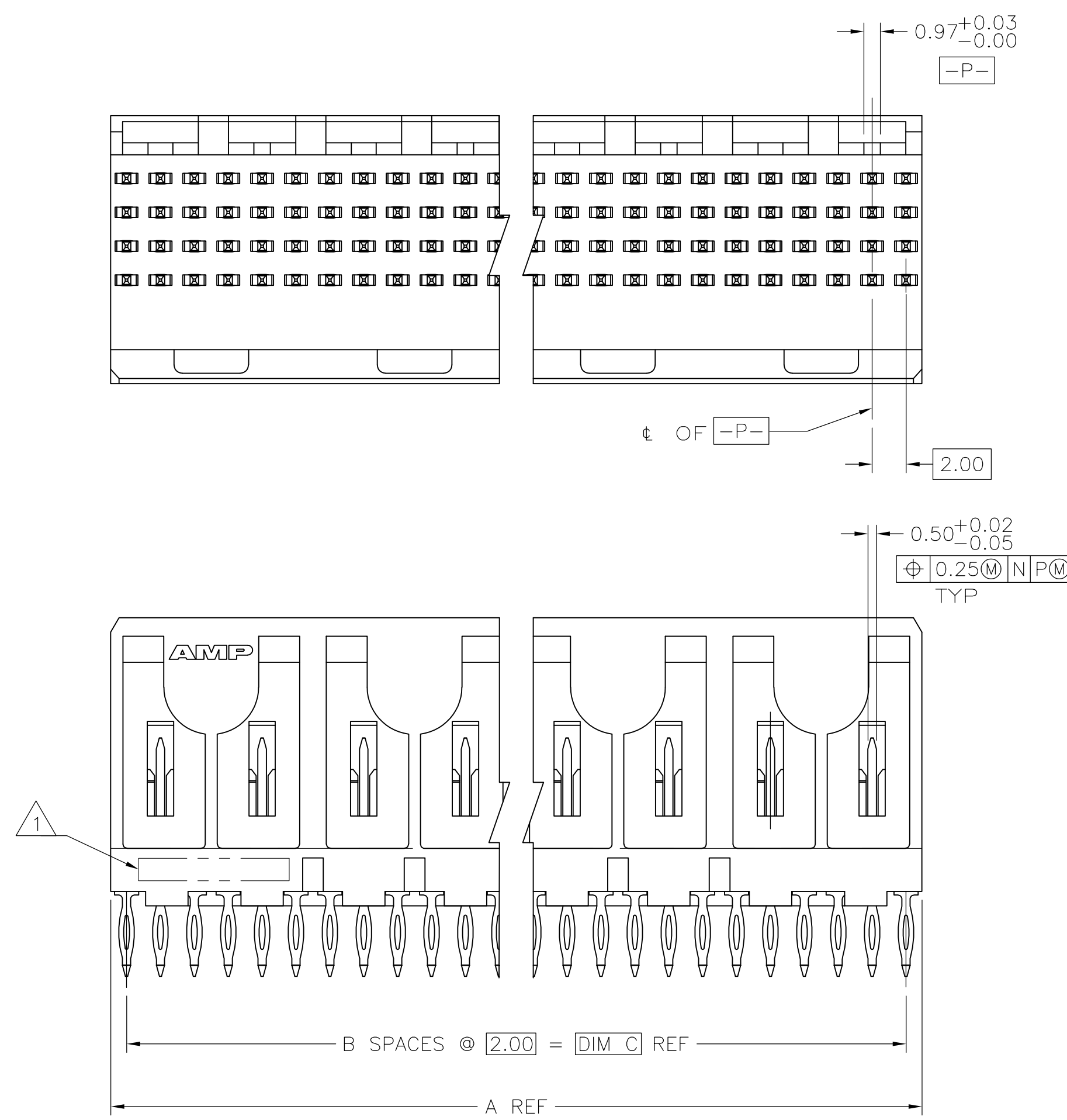
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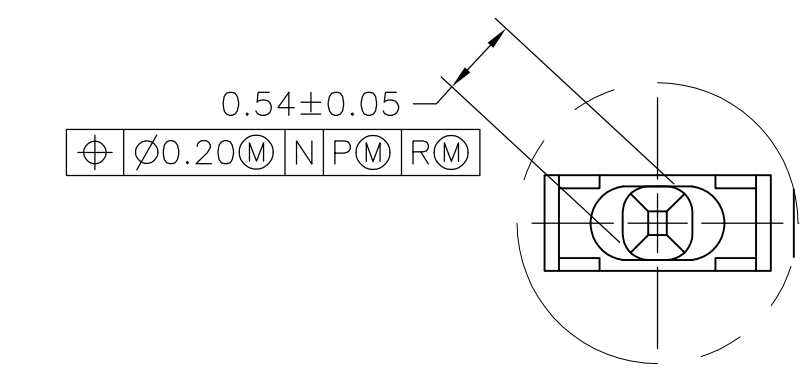
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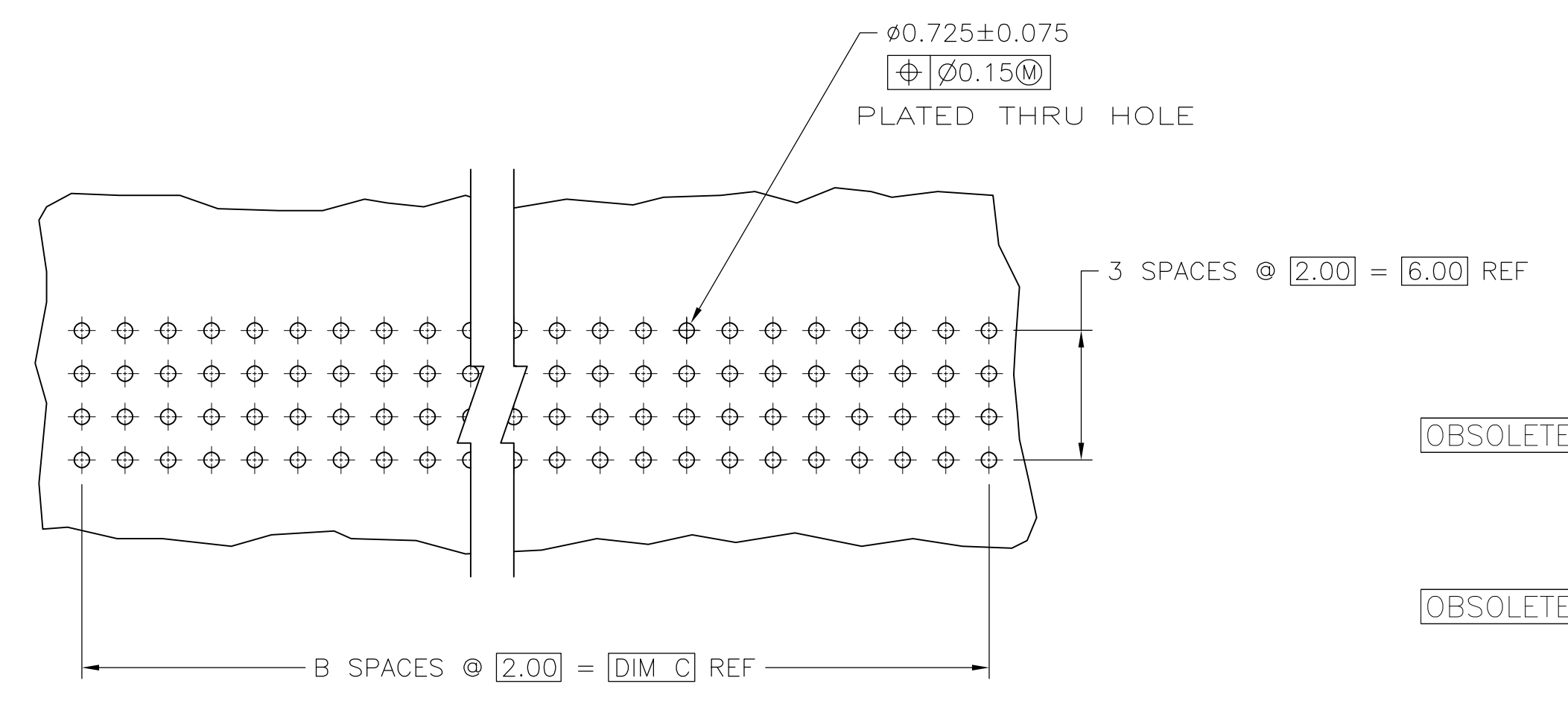
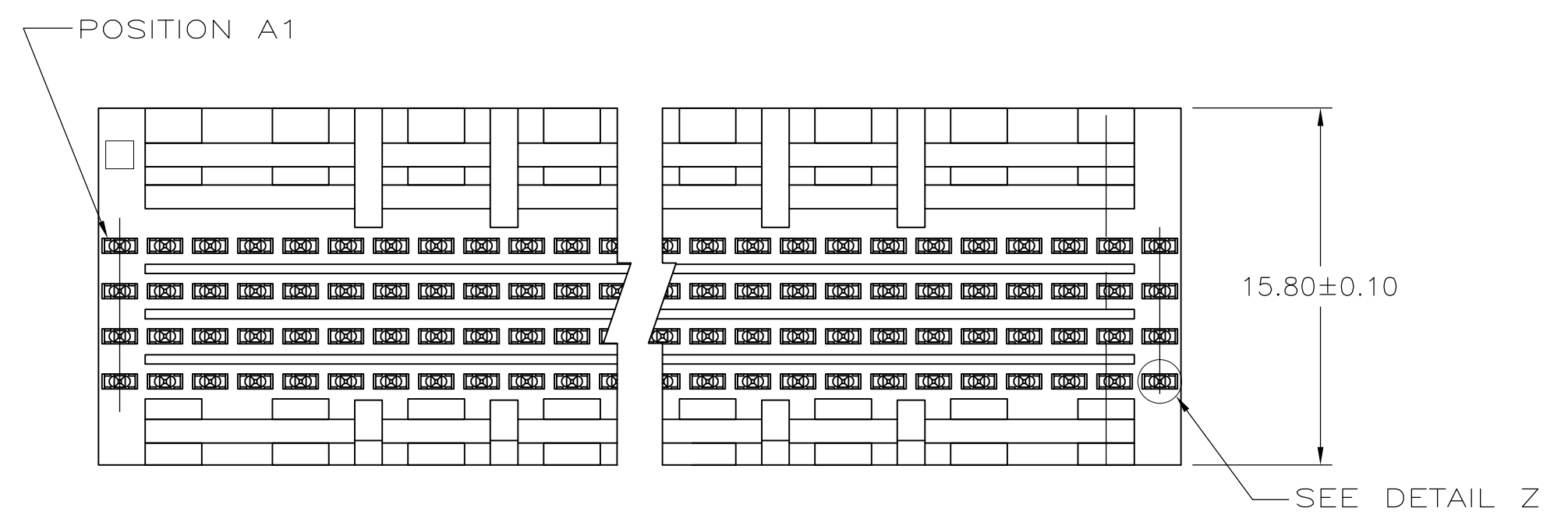




- 1 HOUSING MATERIAL: LIQUID CRYSTAL POLYMER PER ASTM D5138 LCPO00 G30A 32250, COLOR: NATURAL.
- 2 CONTACT MATERIAL: PHOSPHOR BRONZE.
- 3 CONTACT FINISH:
UNDERPLATE (ENTIRE CONTACT):
0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290.
ON MATING SURFACES:
CONFORMS TO ALL TESTING SPECIFIED FOR TELCORDIA UNCONTROLLED ENVIRONMENT.
ON LEADS
0.0006 MIN TIN PER ASTM B 545 OVER UNDERPLATE.
LUBRICATION (MIN MATING SURFACES):
SURFACE CONDITIONER AFTER PLATING.
- 4 PART MARKING, LOCATED APPROXIMATELY AS SHOWN.
- 5 DIMENSION APPLIES WHEN SEATED ON PRINTED CIRCUIT BOARD.
- 6 CONTACT FINISH:
UNDERPLATE (ENTIRE CONTACT):
0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290.
ON MATING SURFACES:
0.00076 MIN NICKEL OR COBALT HARDENED GOLD PER ASTM B-488 OVER UNDERPLATE.
ON LEADS
0.0006 MIN TIN PER ASTM B 545 OVER UNDERPLATE.
LUBRICATION (MIN MATING SURFACES):
SURFACE CONDITIONER AFTER PLATING.



DETAIL Z
SCALE 20:1



RECOMMENDED CIRCUIT PATTERN
PER IPC-D300 TYPE II, CLASS C
(COMPONENT SIDE)

	4.25	46	23	47.88	6	96	3-5536504-3
	4.25	22	11	23.88	6	48	3-5536504-2
	4.25	10	5	11.88	6	24	3-5536504-1
OBSOLETE	4.25	34	17	35.88	3	72	1-5536504-2
	4.25	130	65	131.88	3	264	1-5536504-1
	4.25	106	53	107.88	3	216	1-5536504-0
	4.25	118	59	119.88	3	240	5536504-9
OBSOLETE	4.25	70	35	71.88	3	144	5536504-8
	4.25	66	33	67.88	3	136	5536504-7
	4.25	58	29	59.88	3	120	5536504-6
	4.25	82	41	83.88	3	168	5536504-5
	4.25	94	47	95.88	3	192	5536504-4
	4.25	46	23	47.88	3	96	5536504-3
	4.25	22	11	23.88	3	48	5536504-2
	4.25	10	5	11.88	3	24	5536504-1
	D	C	B	A	FINISH	NO OF POSN	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN: B. MCMASTER 30AUG04
CHK: J.R. WERTZ 30AUG04
APVD: R. WERTZ 30AUG04

TE Connectivity

NAME: PIN ASSEMBLY, SIGNAL MODULE, Z-PACK 2mm FB, 2mm

PRODUCT SPEC: -

APPLICATION SPEC: -

SIZE: A1 CAGE CODE: 00779 DRAWING NO: 5536504

SCALE: 4:1 SHEET: 1 OF 1 REV: B2